

Fast Switching EmCon Diode

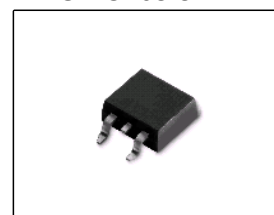
Feature

- 600 V EmCon technology
- Fast recovery
- Soft switching
- Low reverse recovery charge
- Low forward voltage
- 175°C operating temperature
- Easy paralleling
- Qualified according to JEDEC⁰⁾ for target applications

Product Summary

V_{RRM}	600	V
I_F	30	A
V_F	1.5	V
T_{jmax}	175	°C

PG-TO263-3-2



Type	Package	Ordering Code	Marking	Pin 1	PIN 2	PIN 3
IDB30E60	PG-TO263-3-2	-	D30E60	NC	C	A

Maximum Ratings, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	600	V
Continuous forward current	I_F	30	A
$T_C=25\text{°C}$		52.3	
$T_C=90\text{°C}$		34.9	
Surge non repetitive forward current	I_{FSM}	117	
$T_C=25\text{°C}$, $t_p=10\text{ ms}$, sine halfwave			
Maximum repetitive forward current	I_{FRM}	81	
$T_C=25\text{°C}$, t_p limited by T_{jmax} , $D=0.5$			
Power dissipation	P_{tot}	142.9	W
$T_C=25\text{°C}$		142.9	
$T_C=90\text{°C}$		80.9	
Operating and storage temperature	T_j, T_{stg}	-55...+175	°C
Soldering temperature	T_S	245	°C
reflow soldering, MSL1			

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	1.05	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	62	
@ 6 cm ² cooling area ¹⁾		-	35	-	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Reverse leakage current	I_{R}				μA
$V_{\text{R}}=600\text{V}$, $T_{\text{j}}=25^{\circ}\text{C}$		-	-	50	
$V_{\text{R}}=600\text{V}$, $T_{\text{j}}=150^{\circ}\text{C}$		-	-	2500	
Forward voltage drop	V_{F}				V
$I_{\text{F}}=30\text{A}$, $T_{\text{j}}=25^{\circ}\text{C}$		-	1.5	2	
$I_{\text{F}}=30\text{A}$, $T_{\text{j}}=150^{\circ}\text{C}$		-	1.5	-	

⁰J-STD20 and JESD22

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

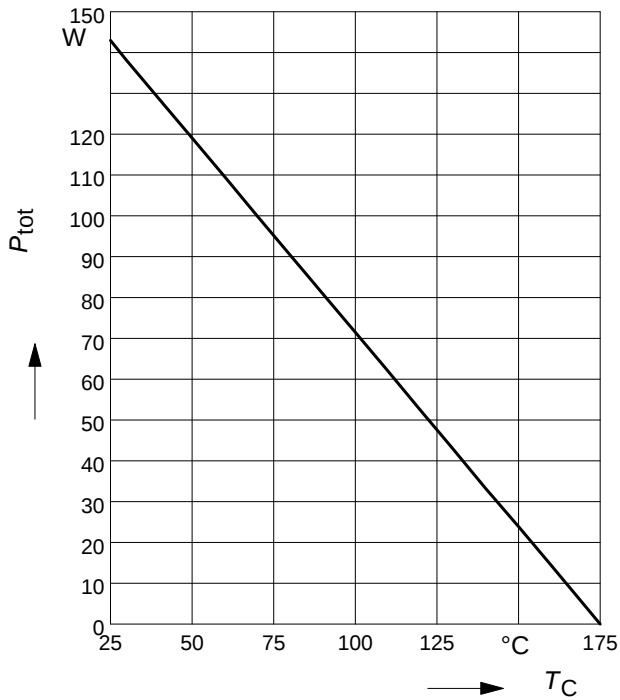
Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Reverse recovery time $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=25^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=125^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=150^{\circ}C$	t_{rr}	- - -	126 171 178	- - -	ns
Peak reverse current $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=25^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=125^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=150^{\circ}C$	I_{rrm}	- - -	19 22 24	- - -	A
Reverse recovery charge $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=25^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=125^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=150^{\circ}C$	Q_{rr}	- - -	1100 1950 2150	- - -	nC
Reverse recovery softness factor $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=25^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=125^{\circ}C$ $V_R=400V$, $I_F=30A$, $di_F/dt=1000A/\mu s$, $T_j=150^{\circ}C$	S	- - -	4 4.6 4.8	- - -	

1 Power dissipation

$$P_{\text{tot}} = f(T_C)$$

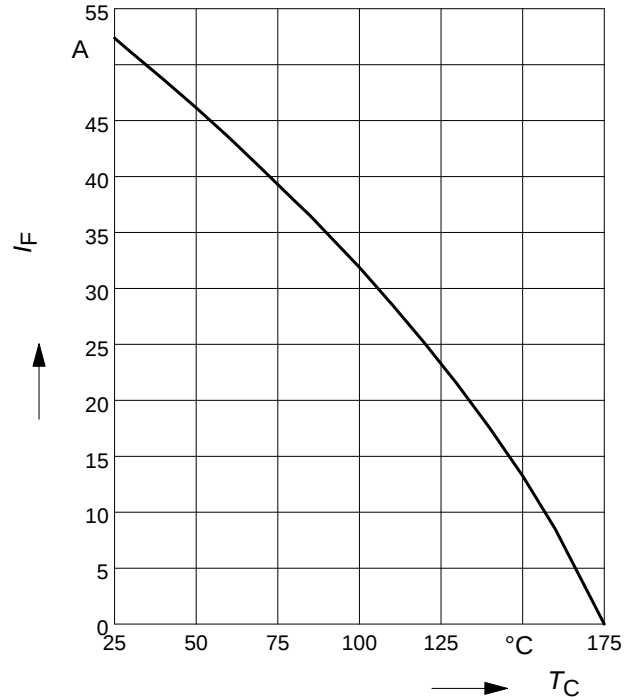
parameter: $T_j \leq 175^\circ\text{C}$



2 Diode forward current

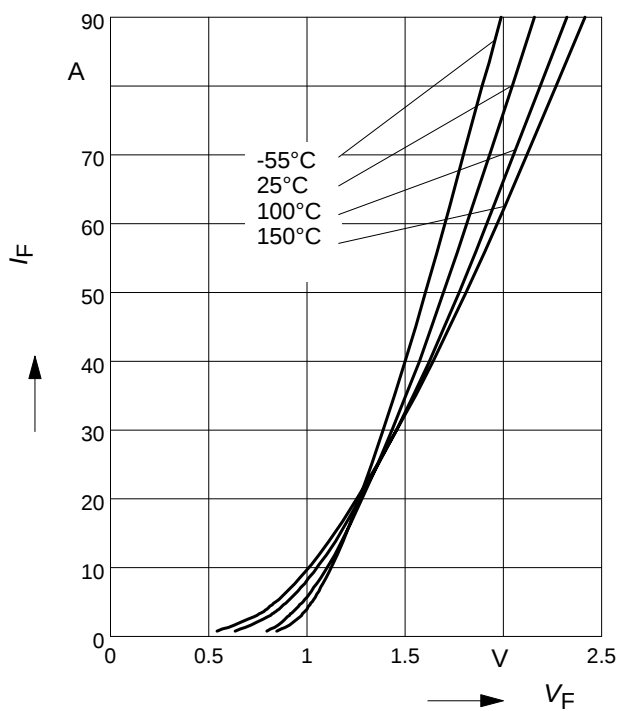
$$I_F = f(T_C)$$

parameter: $T_j \leq 175^\circ\text{C}$



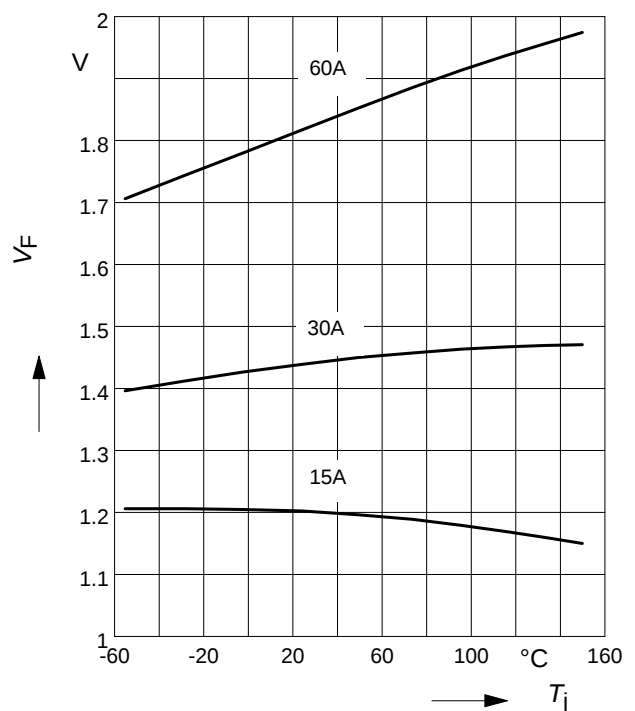
3 Typ. diode forward current

$$I_F = f(V_F)$$



4 Typ. diode forward voltage

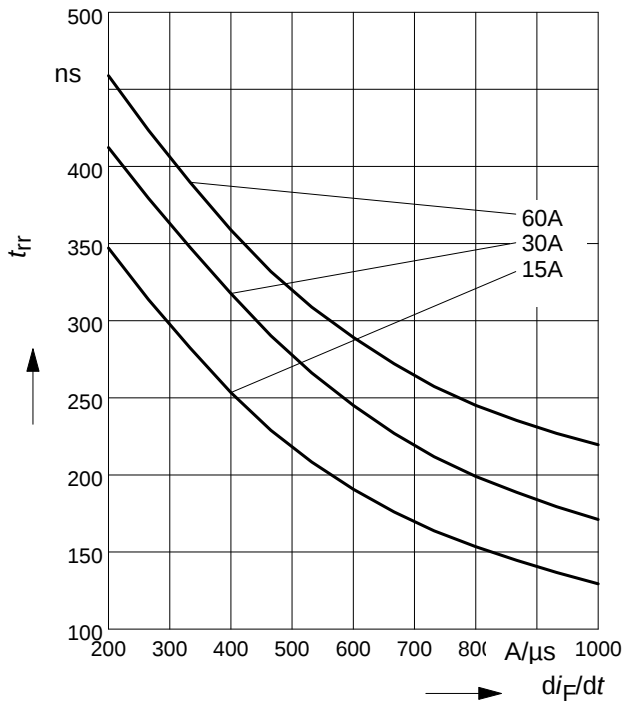
$$V_F = f(T_j)$$



5 Typ. reverse recovery time

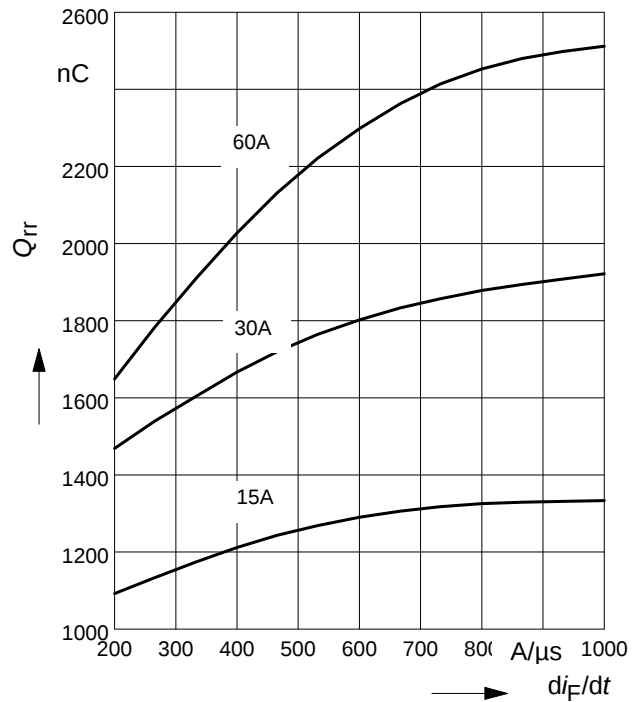
$$t_{rr} = f(dI_F/dt)$$

parameter: $V_R = 400V$, $T_j = 125^\circ C$


6 Typ. reverse recovery charge

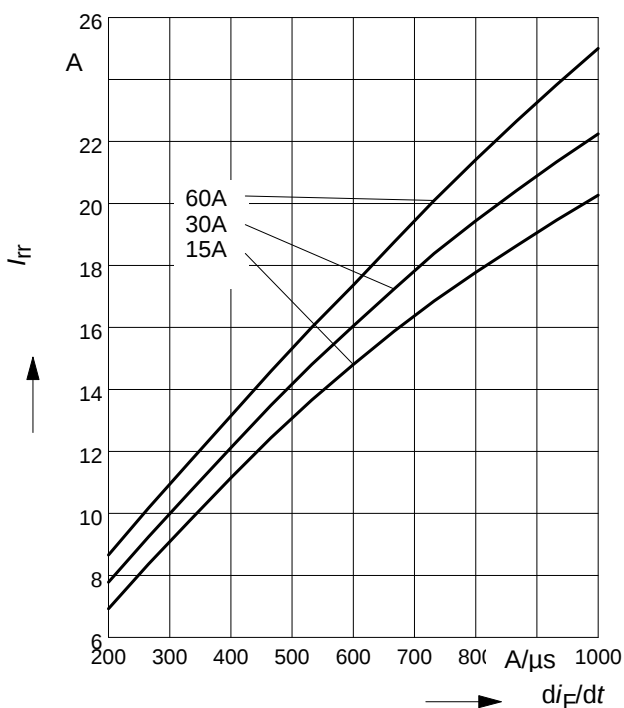
$$Q_{rr} = f(dI_F/dt)$$

parameter: $V_R = 400V$, $T_j = 125^\circ C$


7 Typ. reverse recovery current

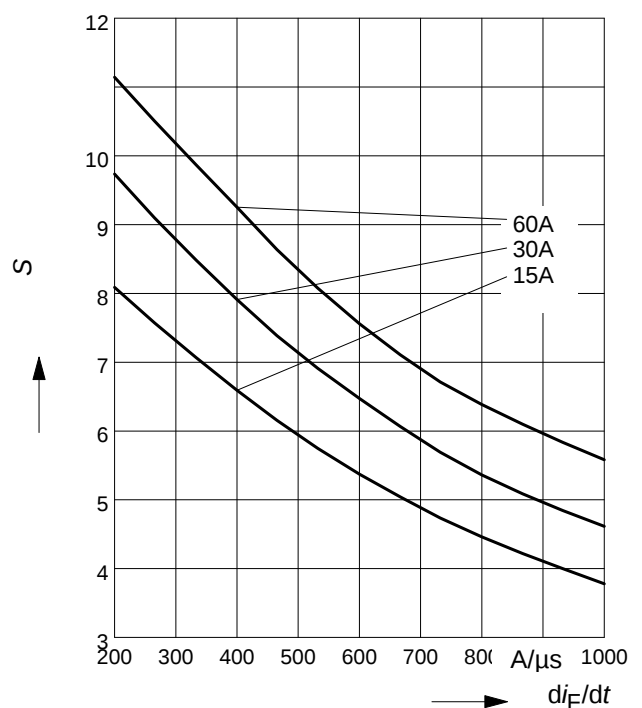
$$I_{rr} = f(dI_F/dt)$$

parameter: $V_R = 400V$, $T_j = 125^\circ C$


8 Typ. reverse recovery softness factor

$$S = f(dI_F/dt)$$

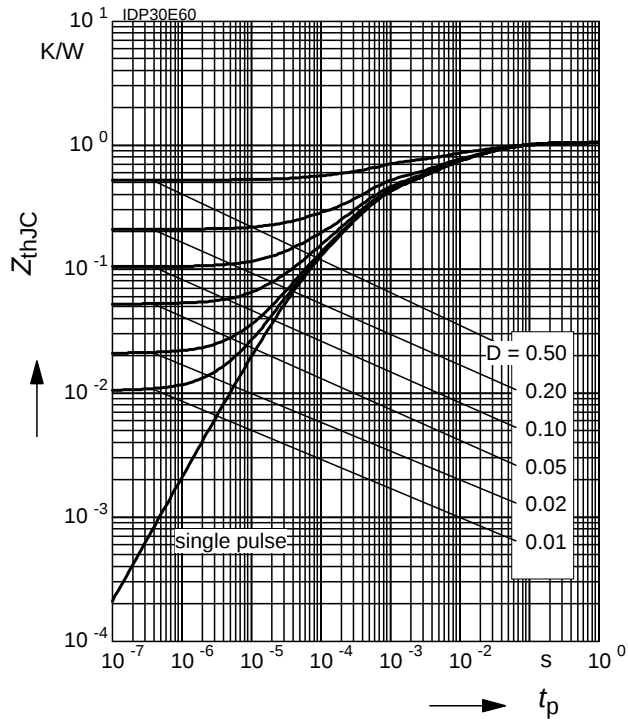
parameter: $V_R = 400V$, $T_j = 125^\circ C$

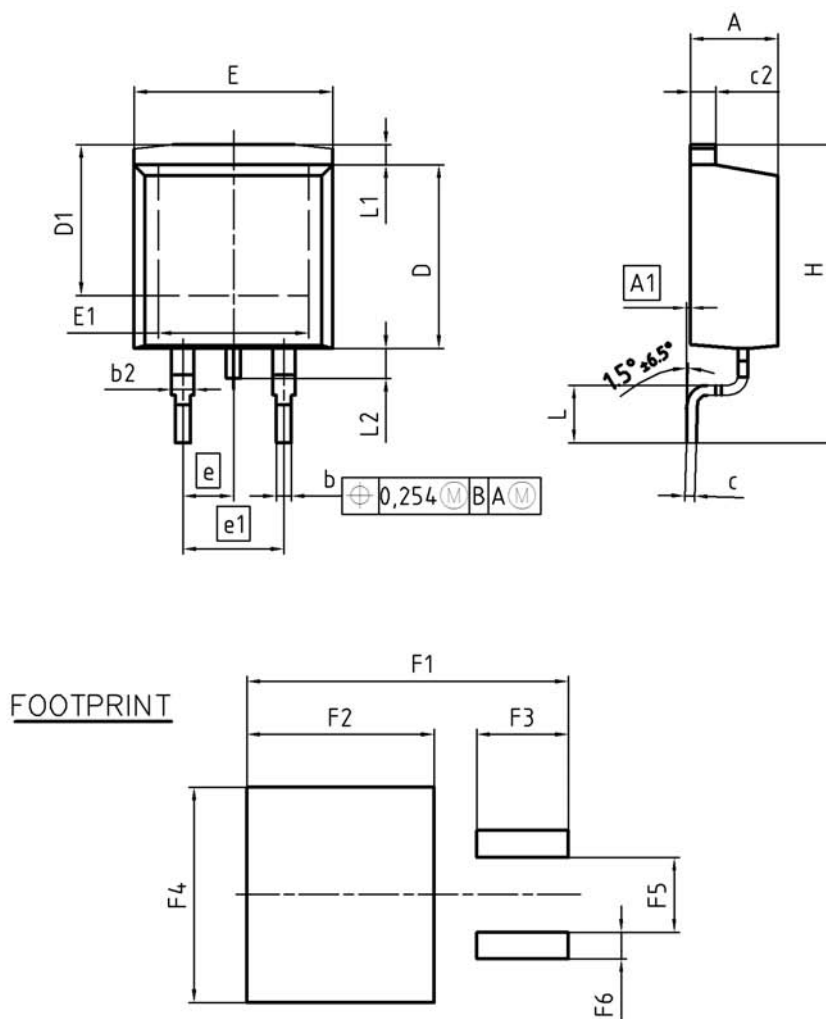


9 Max. transient thermal impedance

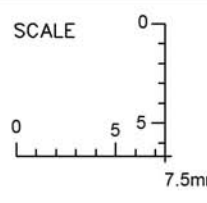
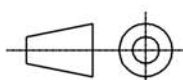
$$Z_{thJC} = f(t_p)$$

parameter : $D = t_p/T$





DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	0.00	0.25	0.000	0.010
b	0.65	0.85	0.026	0.033
b2	0.95	1.15	0.037	0.045
c	0.33	0.65	0.013	0.026
c2	1.17	1.40	0.046	0.055
D	8.51	9.45	0.335	0.372
D1	7.10	7.90	0.280	0.311
E	9.80	10.31	0.386	0.406
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	2		2	
H	14.61	15.88	0.575	0.625
L	2.29	3.00	0.090	0.118
L1	0.70	1.60	0.028	0.063
L2	1.00	1.78	0.039	0.070
F1	16.05	16.25	0.632	0.640
F2	9.30	9.50	0.366	0.374
F3	4.50	4.70	0.177	0.185
F4	10.70	10.90	0.421	0.429
F5	3.65	3.85	0.144	0.152
F6	1.25	1.45	0.049	0.057

DOCUMENT NO. Z8B00003324	
SCALE	
EUROPEAN PROJECTION	
	
ISSUE DATE 30-08-2007	
REVISION 01	

Published by
Infineon Technologies AG,
Bereichs Kommunikation
St.-Martin-Strasse 53,
D-81541 München
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